CGS74LCT2524

CGS74LCT2524 1 to 4 Minimum Skew (300 ps) 3V Clock Driver



Literature Number: SNOS710C



CGS74LCT2524

OBSOLETE

September 21, 2011

1 to 4 Minimum Skew (300 ps) 3V Clock Driver

General Description

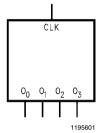
This minimum skew clock driver is a 3V option of the current CGS74CT2524 Minimum Skew Clock Driver and is designed for Clock Generation and Support (CGS) applications operating at low voltage, high frequencies. This device guarantees minimum output skew across the outputs of a given device.

Skew parameters are also provided as a means to measure duty cycle requirements as those found in high speed clocking systems. This minimum skew clock driver with one input driving four outputs, is specifically designed for signal generation and clock distribution applications.

Features

- Ideal for low power/low noise high speed applications
- Guaranteed:
 - 300 ps pin-to-pin skew (t_{OSHI} and t_{OSLH})
- Implemented on National's FACT[™] family process
- 1 input to 4 outputs low skew clock distribution
- Symmetric output current drive: 12 mA I_{OH}/I_{OI}
- Industrial temperature of -40°C to +85°C
- 8-pin SOIC package
- Low dynamic power consumption above 20 MHz
- Guaranteed 2 kV ESD protection

Logic Symbol



The output pins act as a single entity and will follow the state of the CLK when the clock distribution chip is selected.

Pin Description

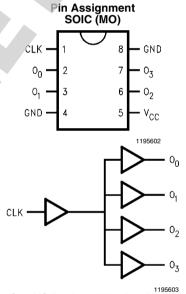
Pin Names	Description
CLK	Clock Input
O ₀ -O ₃	Outputs

Truth Table

Inputs CLK	Outputs O ₀ –O ₃		
L	L		
Н	Н		

L = Low Logic Level H = High Logic Level

Connection Diagrams



See NS Package Number M08A

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Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V_{CC}) -0.5V to 7.0V

DC Input Voltage Diode Current ($I_{\rm IK}$)

 $V = -0.5V \\ V = V_{CC} + 0.5V \\ DC \ Input \ Voltage \ (V_I) \\ -0.5V \ to \ V_{CC} + 0.5V$

DC Output Diode Current (I_O)

V = -0.5V -20 mA $V = V_{CC} + 0.5V$ +20 mA

DC Output Voltage (V_O) -0.5V to V_{CC} +0.5V

DC Output Source or Sink Current

 (I_O) ±50 mA

 $DC \ V_{CC} \ or \ Ground \ Current$

per Output Pin (I_{CC} or I_{GND}) ±50 mA

Storage Temperature (T_{STG}) -65° C to $+150^{\circ}$ C Junction Temperature (θ_{1A})

Airflow 0 225 500 LFM M 167 132 117 °C/W

Recommended Operating Conditions

 $\begin{array}{lll} \text{Supply Voltage (V_{CC})} & 3.0 \text{V to } 3.6 \text{V} \\ \text{Input Voltage (V_{IN})} & 0 \text{V to } V_{\text{CC}} \\ \text{Output Voltage (V_{O})} & 0 \text{V to } V_{\text{CC}} \end{array}$

Operating Temperature (T_A)

(0.8V to 2.0V)

Note 1: The Absolute Maximum Flatings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the DC and AC Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The Recommended Operating Conditions will define the conditions for actual device operation.

DC Electrical Characteristics

Over recommended operating conditions unless specified otherwise.

Symbol	Parameter Conditions		CGS74LCT2524				
		Conditions	V _{CC}	T _A = +25°C		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	Units
				Typ Guaranteed Limits		aranteed Limits	
V _{IH}	Minimum High Level Input Voltage	$V_{OUT} = 0.1V \text{ or } V_{CC} = 0.1V$	3.6	1.5	2.0	2.0	V
V _{IL}	Maximum Low Level Input Voltage	$V_{OUT} = 0.1V \text{ or } V_{CC} = 0.1V$	3.6	1.5	0.8	0.8	V
V _{OH}	Minimum High Level	$V_{IN} = V_{IL}$ or V_{IH} , $I_{OUT} = -50 \mu A$	3.0		2.9	2.9	V
	Output Voltage	$V_{IN} = V_{IL}$ or V_{IH} , $I_{OH} = -12$ mA	3.0		2.5	2.4	٧
V _{OL}	Minimum Low Level	$V_{IN} = V_{IL} \text{ or } V_{IH}, 1_{OUT} = 50 \mu\text{A}$	3.0		0.1	0.1	V
	Output Voltage	$V_{IN} = V_{IL}$ or V_{IH} , $I_{OL} = -12 \text{ mA}$	3.0		0.3	0.4	V
I _{IN}	Maximum Input	V _{IN} = V _{CC} , GND	3.6		±0.1	±1.0	μA
	Leakage Current						
I _{CCT}	Maximum I _{CC} /Input	$V_{IN} = 3.0V$	3.6			100	μA
I _{OLD}	Minimum Dynamic	V _{OLD} = 0.8V (max)	3.6			36	mA
I _{OHD}	Output Current	V _{OHD} = 2.0V (min)	3.6			-25	mA
I _{cc}	Maximum Quiescent Supply Current	V _{IN} = V _{CC} or GND	3.6		2.5	10	μА

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AC Electrical Characteristics

Over recommended operating conditions unless specified otherwise. All typical values are measured at $V_{CC} = 3.3V$, $T_A = 25^{\circ}C$

Symbol	Parameter			Units	
		Min	Тур	Max	
t _{PLH}	Low-to-High Propagation Delay	6		15.0	ns
	CLK to O _n				
t _{PHL}	High-to-Low Propagation Delay	6		15.0	ns
	CLK to O _n				

Extended AC Electrical Characteristics

Over recommended operating conditions unless specified otherwise. All typical values are measured at V_{CC} = 3.3V, T_A = 25°C

Symbol	Parameter	$V_{CC} = 3.0V \text{ to } 3.6V$ $V_{A} = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $C_{L} = 50 \text{ pF}$ $R_{L} = 500\Omega$			Units
		Min	Тур	Max	
f _{max}	Maximum Operating Frequency		75		MHz
t _{OSHL}	Maximum Skew Common Edge			300	ps
	Output-to-Output Variation (Note 2)				
t _{OSLH}	Maximum Skew Common Edge			300	ps
	Output-to-Output Variation (Note 2)				
t _{PS}	Maximum Skew			2.5	ns
	Pin (Signal) Transition Variation (Note 3)				
t _{RISE}	Rise Time/Fall Time			2.5	ns
t _{FALL}	(from 0.8V to 2.0V/2.0V to 0.8V)				
T _{HIGH}	Time High	4			ns
T _{LOW}	Time Low	4			ns

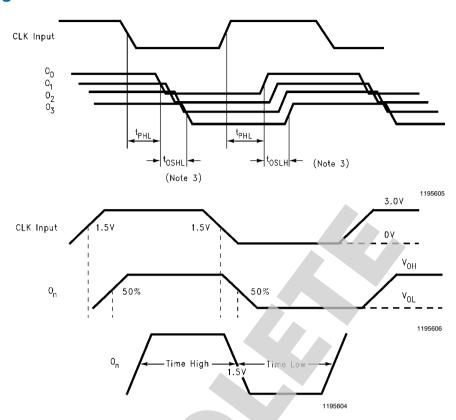
Note 2: Output-to-Output Skew is defined as the absolute value of the difference between the actual propagation delay for any outputs within the same packaged device. The specifications apply to any outputs switching in the same direction either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}) or in opposite directions both HL and LH (t_{OST}). Limits are characterized and guaranteed by design @ 66 MHz.

Note 3: Pin transition skew is the absolute difference between HIGH-to-LOW and LOW-to-HIGH propagation delay, measured at a given output pin.

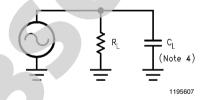
Note 4: Refer to Minimum Skew Parameters Measurement Information Chart for definitions of each skew specification.

Note 5: Load capacitance includes the test jig.

Timing Diagrams



Test Circuit

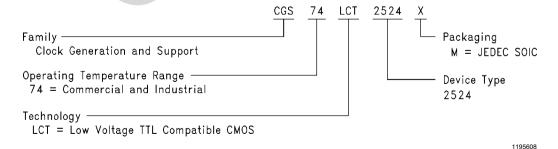


 R_{L} is 500Ω

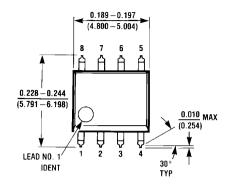
C_L is 50 pF for all propagation delays and skew measurements.

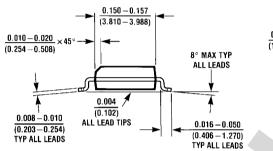
Ordering Information

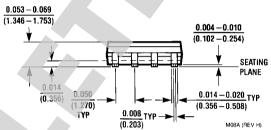
(Contact NSC Marketing for specific date of availability)



Physical Dimensions inches (millimeters) unless otherwise noted







8-Lead (0.150 Wide) Molded Small Outline Package, JEDEC Order Number CGS74LCT2524M NS Package Number M08A

Notes

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